

QUALITEK BGA2005 REWORK SYSTEM



BGA rework system uses micro-processor control and infrared sensor technology to do soldering and desoldering to surface mounted components safely and accurately. It consists of QUALITEK IR2005 Infrared Rework System and QUALITEK PL2005 Precision Placement System.

*The soldering and desoldering process are both under the monitoring of non-contact infrared sensor to get the optimum and reproductive PCB temperature

*The technology of controlling reflow soldering by looped circuit ensures precise temperature window, even heat distribution and suitable peak value of temperature.

*The adjustable aperture can protect the adjacent components (which is sensitive to the temperature) on PCB from being heated. No need for nozzles.

*The use of reflow process camera supplies the critical message to judge the melting situation of solder materials during the whole soldering and desoldering process.

*It can deal with PCB with big thermal capacity and other high temperature situation easily (For example, lead-free soldering).

QUALITEK PL2005 Precision Placement System

PL2005 precision placement system provides accurate alignment control for soldering of IR2005 rework system. Its precision micro-adjustment and alignment information provided by camera ensure IR2005's exact soldering.

QUALITEK 2005 Main Parts:

1. IR2005 Infrared Reflow Soldering System

Infrared temperature sensor monitors BGA surface temperature to ensure precise temperature technical window. Even heat distribution, real closed-loop control.

2. PL2005 Precision Aligning and Placing system

Double-color optical alignment, precise and clear alignment easy to control and place components

3. RPC2005 Reflow Camera

Provide the critical visual information for judging the melting status of solder during the whole soldering and desoldering process.

4. IRsoft Software

By means of PC, the whole process can be recorded, controlled and analyzed and then generate the curve diagram to meet the demands of modern electronic industry.

QUALITEK 2005 Specifications:

IR Infrared Rework System

General Power	1600W (max)
Power of Bottom Heater	400W*2=800W (Dark Infrared Ceramic Heating plate)
Power of Top Heater	180W*4=720W (Infrared heating tube, wave length)
Size of Top Heater	60*60mm
Size of Bottom Heater	135*250mm
Adjusting Range of Top Heater	20-60(X, Y direction both adjustable)
Vacuum Pump	12V/300Ma, 0.05Mpa (max)
Top Cooling Fan	12V/300Ma 15CFM

Laser Alignment Tube	3V/30mA
Movable Motor	24VDC/100mA
Movable Arm Range	93mm
Max PCB Size	300mm*300mm
LCD Display Window	65.7*23.5mm 16*2 alphabet
Soldering Station	Intelligent Digital Lead Free Soldering Station: 60W
Soldering Power	60W
Communication	RS-232C (connect with PC)
Infrared Temperature Sensor	0-300°C (Testing Range)
Outside K type Sensor	Optional
Weight	13Kg

PL Precision Placement System

Power	About 15W
Camera	22*10 times magnifying;12V/300Ma; Horizontal resolution: 480 lines; PAL format
Size of BGA to be aligned	40mm*40mm
LED Lighting	White LED (low side), Red LED (upper side) (Brightness adjustable)
Vacuum Pump	12V/600Ma 0.05Mpa (max)
Camera Output Signal	Video Signal
Weight	22Kg

RPC Reflow Soldering Process Camera

Power	About 15W
Camera	22*10 times magnifying; 12V/300mA; Horizontal resolution: 480 lines; PAL format
LED Lighting	White LED (brightness Adjustable)

Note: without additional notice if above parameter change.